Special Issue

Emerging Methods in Digital Manufacturing

Message from the Guest Editors

I would like to draw your attention to this Special Issue of JMMP. Digital manufacturing is experiencing revolutionary changes thanks to new methods such as additive manufacturing (3D printing), robotic automation, the Internet of Things (IoT), and artificial intelligence. These technologies enable the creation of more complex and personalized products with greater accuracy and efficiency. Modern approaches bring improvements in the fields of quality control, waste reduction, and optimization of production processes, thereby increasing the competitiveness and innovation potential of companies. The scope of this Special Issue includes, but is not limited to, the following:

- Digital manufacturing;
- IoT:
- Flexible manufacturing;
- ERP systems;
- Industry 4.0;
- Sustainable manufacturing;
- Al-supported manufacturing.

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About the Journal

Message from the Editor-in-Chief

Journal of Manufacturing and Materials Processing (JMMP)(ISSN 2504-4494) is a new MDPI peer-reviewed, open access venue with a focus on the scientific fundamentals and engineering methodologies of manufacturing and materials processing. We offer an online platform facilitating effective exchange of innovative scientific and engineering ideas and the dissemination of recent, original, and significant research and developmental findings. On behalf of the Editorial Board, I extend an invitation to our scientific and engineering colleagues to contribute high-quality, innovative, and ground-breaking research articles to .IMMP.

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